

Title (en)  
EPOXY RESIN BASED SOLDER PASTE

Title (de)  
Lötpaste auf Epoxidharzbasis

Title (fr)  
PATE A SOUDER A BASE DE RESINE EPOXY

Publication  
**EP 0870329 A1 19981014 (EN)**

Application  
**EP 96928056 A 19960809**

Priority  
• US 9612761 W 19960809  
• US 51404995 A 19950811  
• US 64491196 A 19960528

Abstract (en)  
[origin: WO9707542A1] A method of making low and high mass assemblies at surface mount profile conditions utilizing a solder paste have a binder comprised of a thermosetting resin and cross-linking agent that also acts as a flux is described. The method of selecting the components and specific binders, including binders with a catalyst such as tin octoate are also described. The binder utilized has a gel point that is at or above the melting point of the solder powder and most preferably above such melting point.

IPC 1-7  
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IPC 8 full level  
**B23K 1/00** (2006.01); **B23K 1/008** (2006.01); **B23K 3/06** (2006.01); **B23K 35/02** (2006.01); **B23K 35/22** (2006.01); **B23K 35/36** (2006.01); **B23K 35/363** (2006.01); **C08G 59/68** (2006.01); **H01L 21/56** (2006.01); **H05K 3/28** (2006.01); **H05K 3/34** (2006.01); **H05K 3/32** (2006.01)

CPC (source: EP KR)  
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Citation (search report)  
See references of WO 9707542A1

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